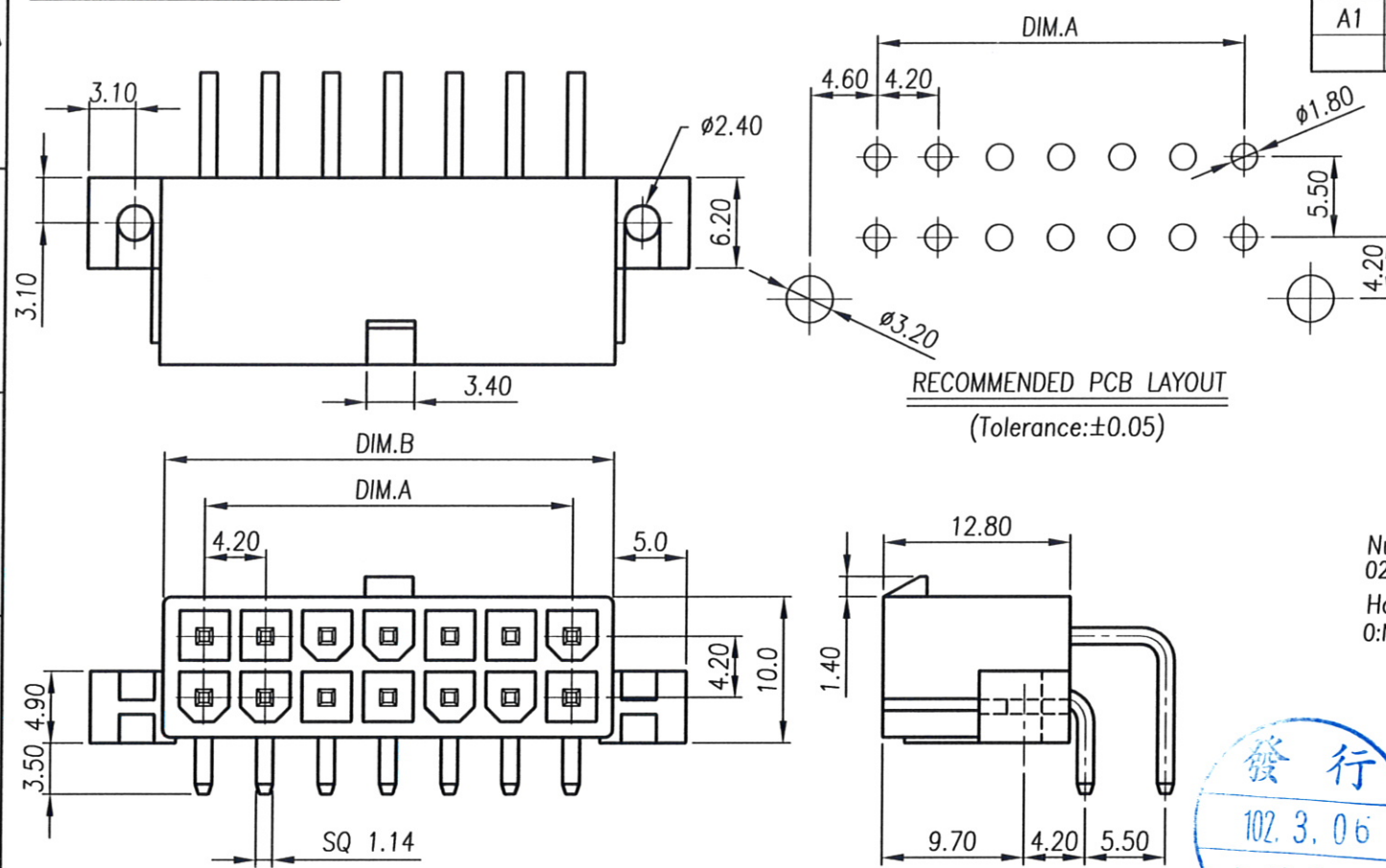


RoHS Compliant

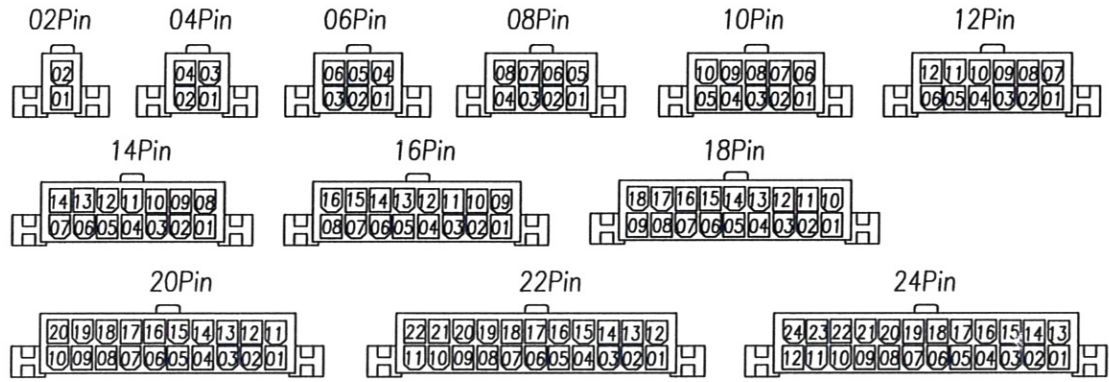


REV	MODIFICATION	DATE	DRAW
A0	Release To Production	2010.04.20	AJ
A1	ECN20130202	2013.02.26	Seven



Specification  
 1.Current Rating:9A  
 2.Voltage Rating:600V AC/DC  
 3.Contact Resistance:10mΩ Max.  
 4.Insulation Resistance:1000MΩ Min. At DC 500V.  
 5.Dielectric Withstanding Voltage:AC 1500V/Minute  
 6.Operating Temperature:-40°C~+105°C  
 7.Applicable PC Board Thickness:0.8~1.6mm  
 Material:  
 1.Housing:Thermoplastic UL94V-2  
 2.Contact Pin:Copper Alloy SQ Pin=1.14mm  
 Finish:  
 1.Housing:Natural  
 2.Contact Pin:Bright Tin Plated  
 Part No.: AD01201 XX 0 1 5 C  
 Number Of Pin 02~24  
 Housing Material 0:NY66 UL94V-2 Natural  
 Packing 5:Bag  
 Plating 1:Bright Tin Plated Over Nickel All.

PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B
02	4.2	5.6	14	25.2	30.8
04	8.4	9.8	16	29.4	35.0
06	12.6	14.0	18	33.6	39.2
08	16.8	18.2	20	37.8	43.4
10	21.0	22.4	22	42.0	47.6
12	25.2	26.6	24	46.2	51.8



**金上達科技股份有限公司**  
**GOLDENSUNDA TECHNOLOGY CO.,LTD**

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 4.20mm 90° Dual Row DIP With Pegs	
.x± 0.35	x'± 2'	APR. Jay 20130226	PART NO. AD01201XX015C	DWG NO. AD01201XX015C
.xx± 0.25	.x'± 1'	CHK. Michelle 20130226	UNITS: mm	
.xxx± 0.15	.xx'± 0.5'	DRA. Seven 20130226	CUSTOMER DRAWING	
		SIZE: <b>A4</b>	SCALE 2:1	SHEET 1 / 1
			REV A1	V